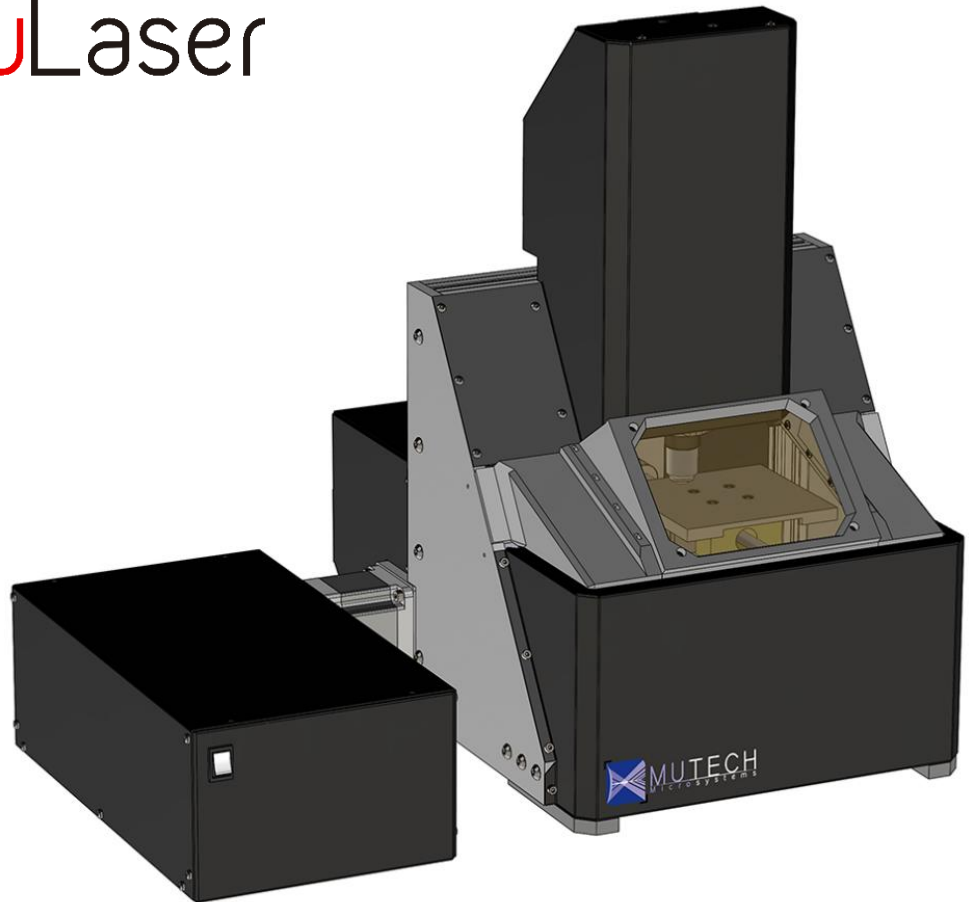# μLaser

Features

- 100x92 mm^2 writing area

- 3-5µm feature size

- Options for writing on SU8/Epoxy photoresists

- Ultra compact design ideal for fume hood or glove box usage

- Integrated confocal microscope for laser focusing, aligning and inspection

- Laser spot size can be changed using industry standard microscope objectives

- Tilted/warped substrate compensation via 3-point focus or 4-point bilinear measurement

- Multiple designs from different files can be written in one process

Mutech microlaser

Mutech microsystems microlaser is a high value direct laser lithography writer, oriented to universities and research facilities looking to expand their capabilities.

It writes on a photosensitive resist coated surface with a laser at submicron pixel resolution on big areas.

You can write anything from photomasks to research prototypes for basic or applied science

Microlaser comes with a confocal integrated camera and yellow illumitation to focus the laser, align the writing with existing features and to inspect the designs after writing.

Direct laser lithography

Direct laser lithography greatly reduces costs and execution times in areas such as microfluidics, microelectronics, micromechanics and material science research, by eliminating the dependence of external suppliers for the production of photomasks.

Ultra compact design

microLaser size is only 510x360x455mm and weighs 16kg, making it ideal for use inside of a fume hood or a glove box simplifying installation, reducing requirements and improving the cleanliness of microfabrication processes.
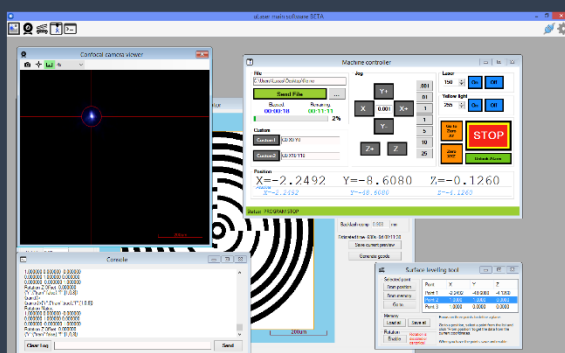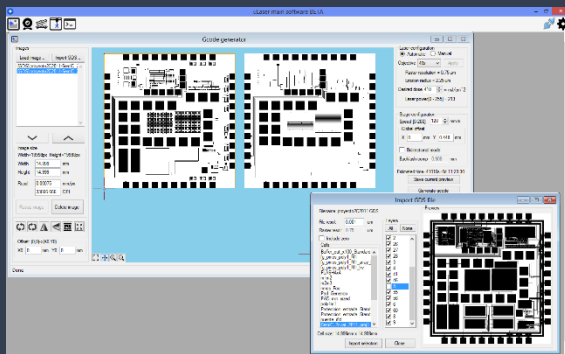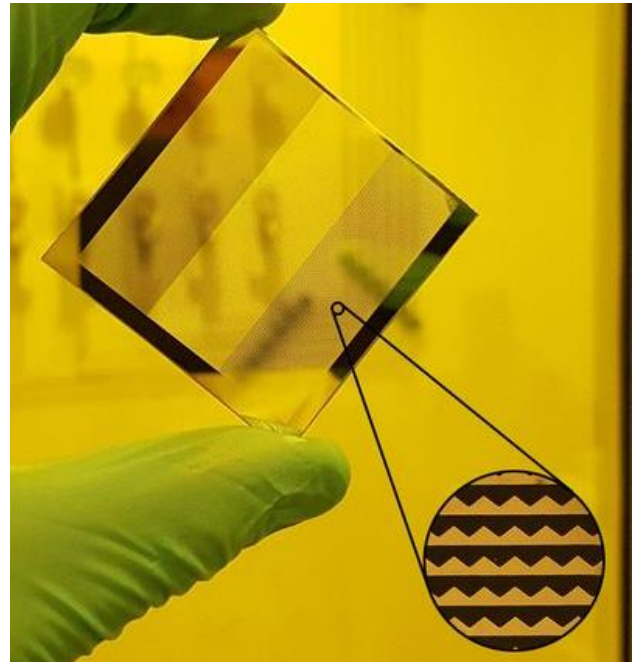
Software

μLaser is delivered with its control software on a PC. It allows you to import the designs to be written from cells of GDSII files or directly from PNG images.

Everything is done from a user friendly graphical interface that allows you preview the design to write before executing it.

Multiple designs can be combined in a single process, in addition to applying transformations such as rotations, reflections, inversions or scale adjustments to each design.

The writings can be aligned with previous designs on the substrate using the confocal camera.

Technical specifications

Mechanics

|	
Size (WxDxH)	510 x 360 x 455 mm
Weight	16 kg
Power	110v/220v 400w

XY stage

Typical writing speed	100-120 mm/s
Maximum area	100x92 mm^2
Unidirectional positioning step	X = 0.16 µm, Y = 1.00 µm
Mechanical noise on the X and Y axis	< 1 µm
Multi layer aligning accuracy	5-10 µm (Optional rotary stage for easier aligning)
Realistic minimum feature size: 3-5µm depending on the feature	

Software

|	
Supported formats	PNG,GDSII
In-software transformations	Rotation, Reflection, Inversion, Rescaling, Add border
Multiple designs from different files can be written in one process	
Tilted/warped substrate compensation via 3-point linear or 4-point bilinear focus measurement	
Mesh type calibration for full-bed curvature compensation	
Unidirectional or bidirectional writing modes	

Optics

Laser wavelength	405nm (Optional 375nm)
Confocal microscope for laser focusing, aligning and inspection	
Secondary independent yellow illumination	
Laser spot size can be changed using industry standard microscope objectives	

Included objectives

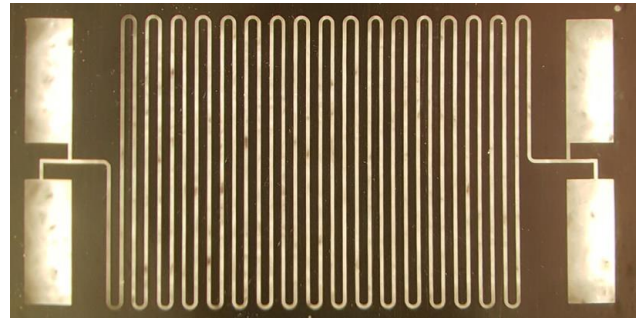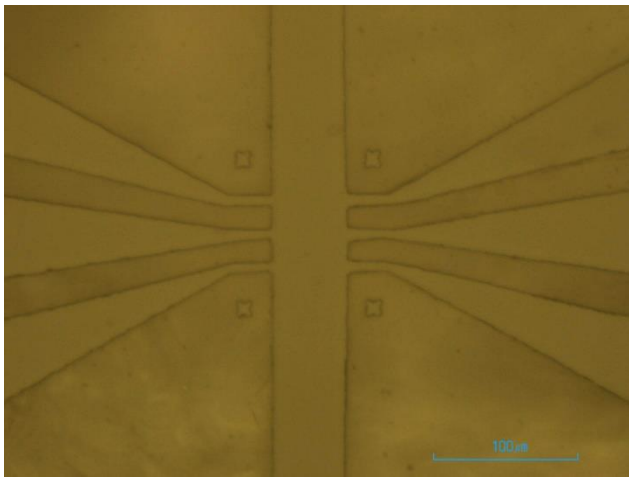|	Raster step	Speed on big areas (unidirectional)
Fine	0.8 µm	1.7 mm^2/min
Medium-fine	0.96 µm	2.04 mm^2/min
Medium	2 µm	4.25 mm^2/min
Coarse	5 µm	10.6 mm^2/min
Speed doubles in bidirectional writing mode		

Optional rotary stage for aligning
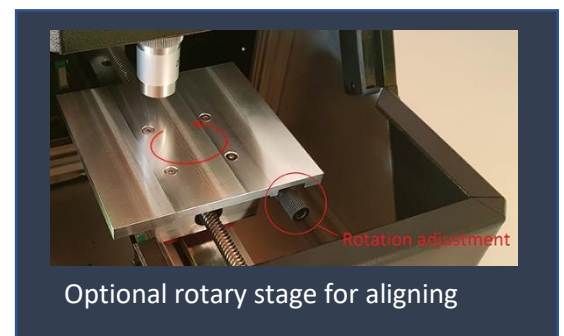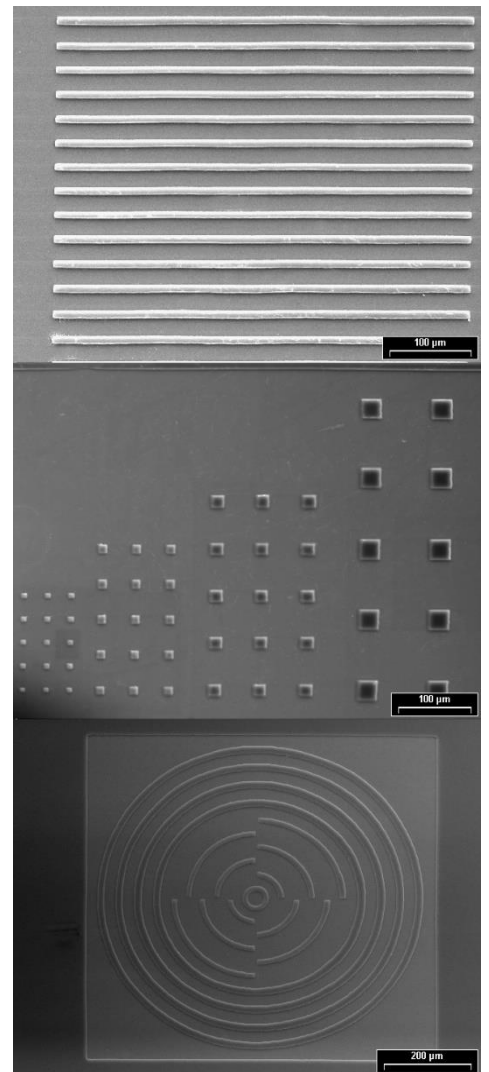
Examples: Electrical transport
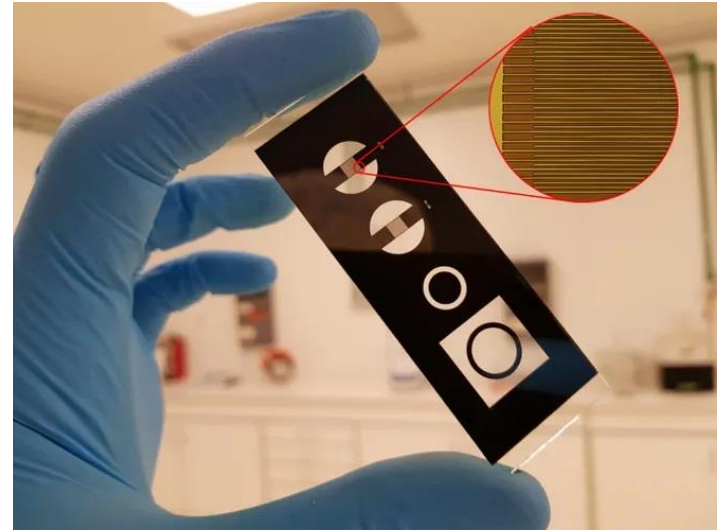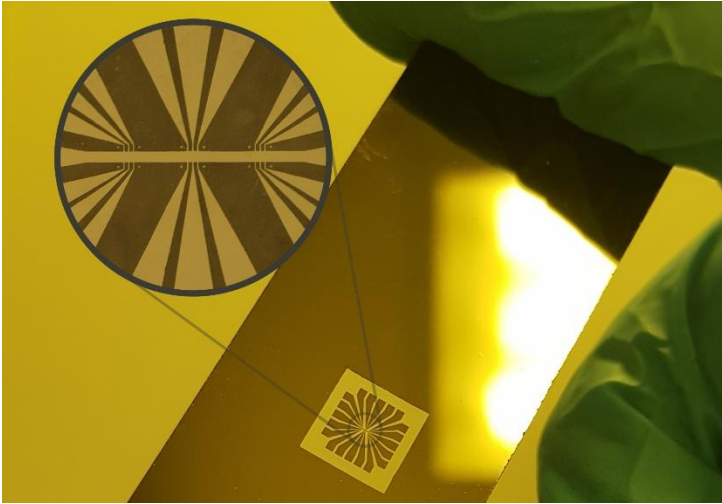
Full microscope slide mask with small 12 μm features
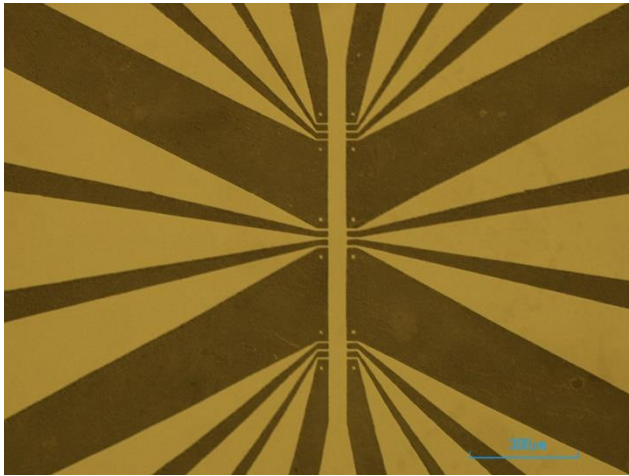
10 μm interdigitated capacitor

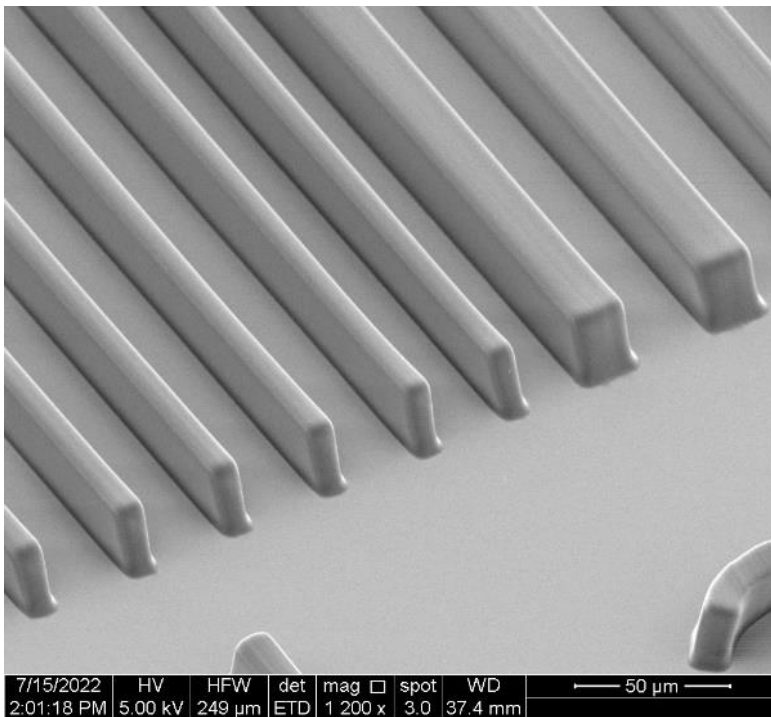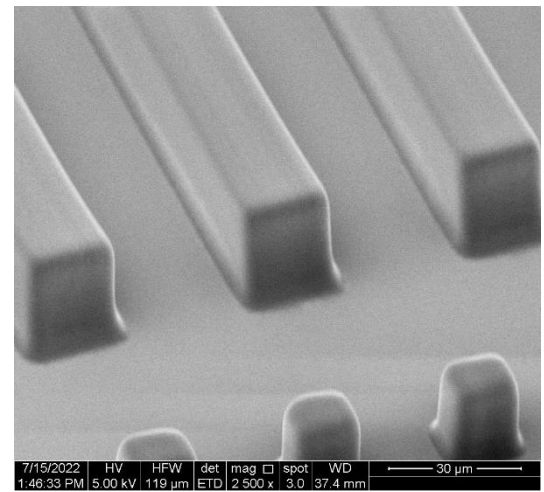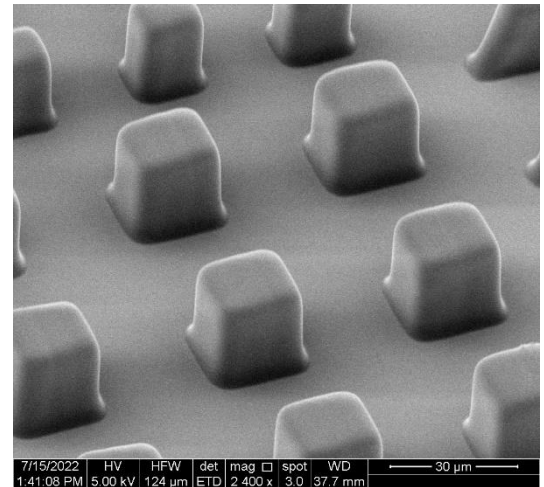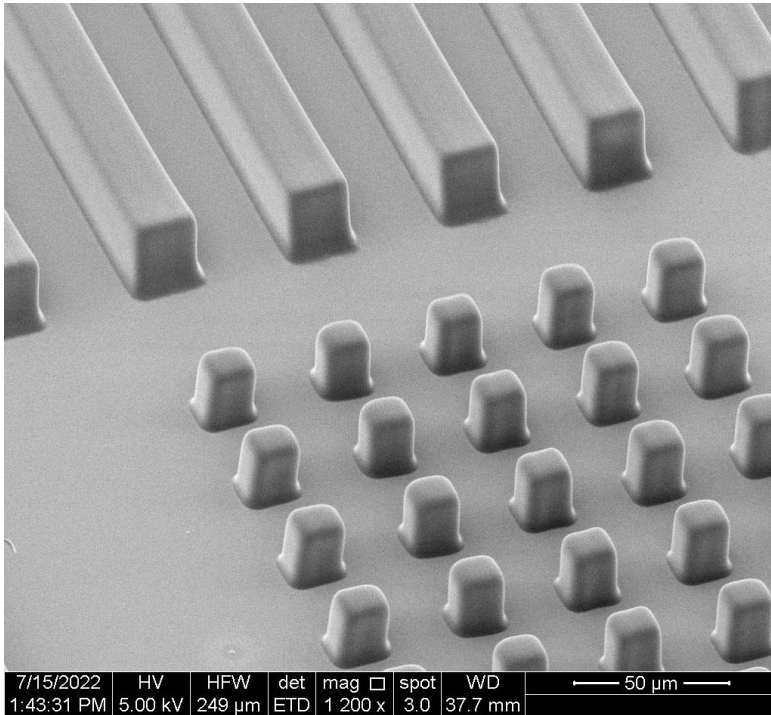Current and voltage contacts with longitudinal and parallel configuration for hall current measurements
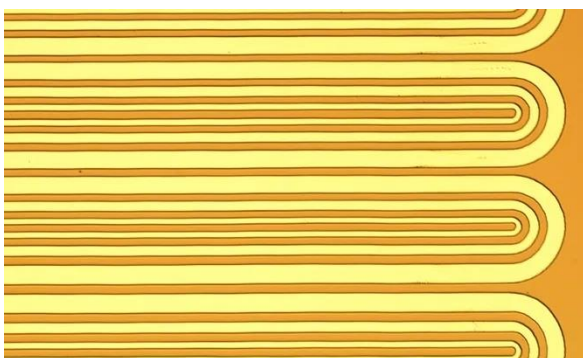

Mask for a platinum resistor for temperature measurement (40 μm track)

Examples: SU-8 Writing
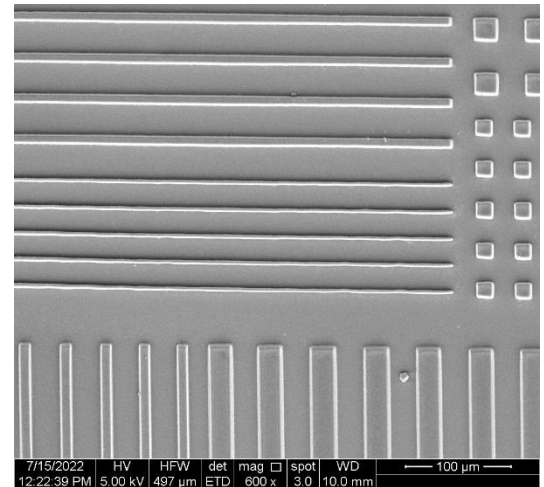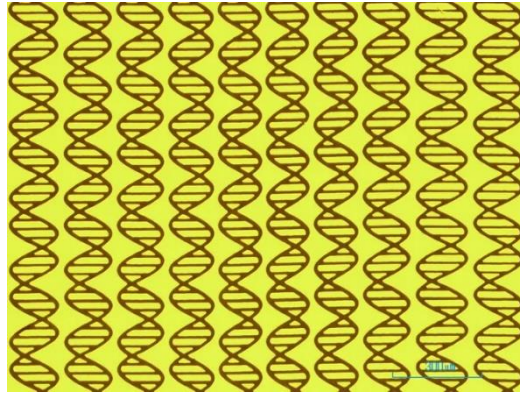
Examples: Microfluidics
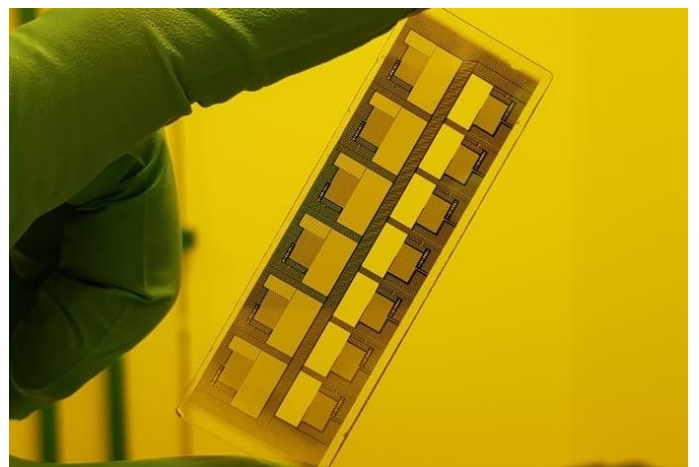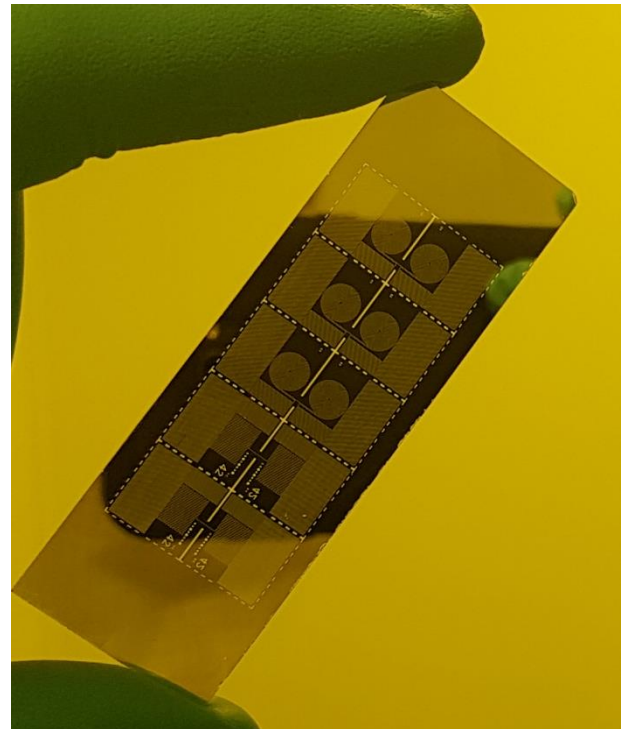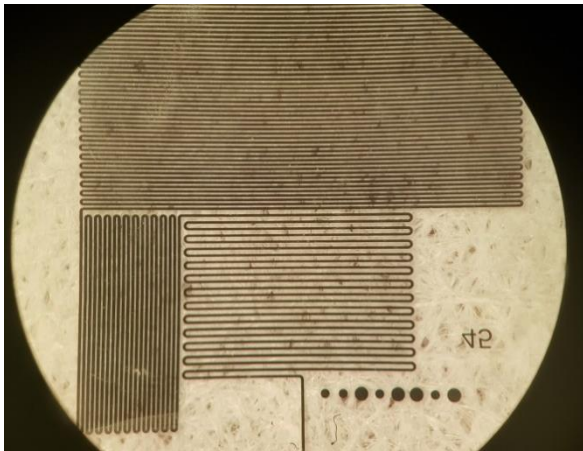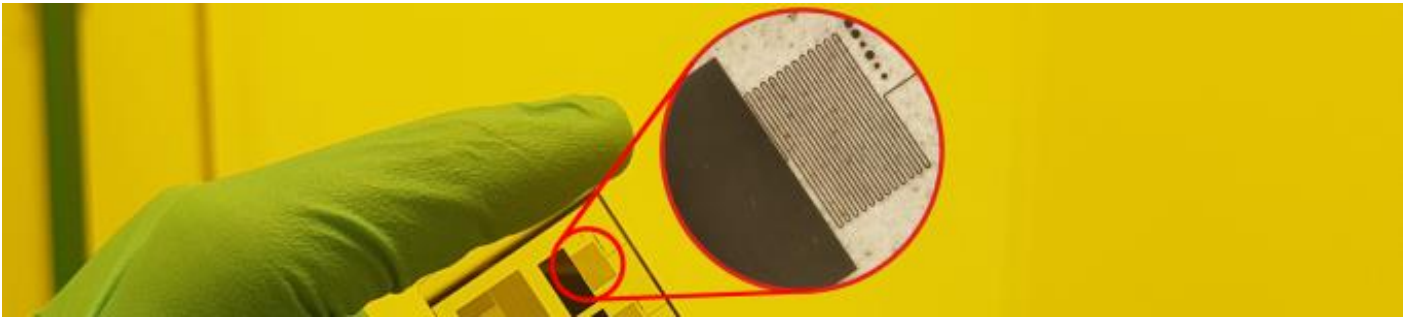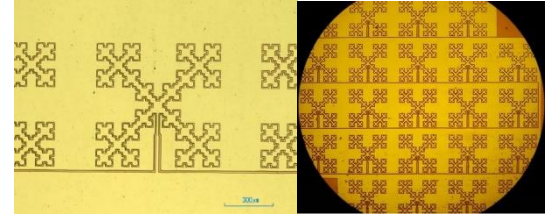
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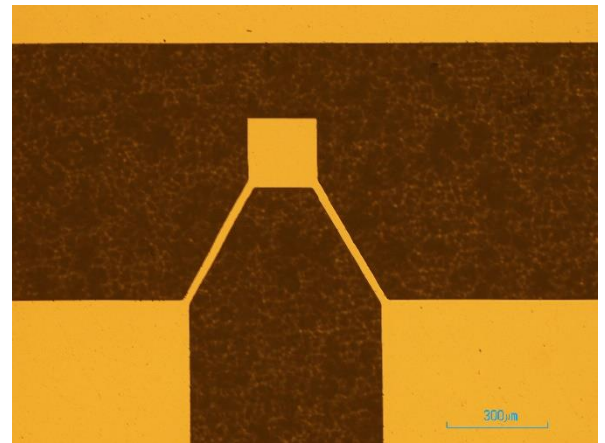
Examples: Other uses

DNA diffraction writing

Fractal micro antennas

Positive and negative text

MEMS oscillator

Low resolution (fast) mode

This demo is using the 4x objective with 5 µm raster step
- The tracks of the example are 50 µm
- This writing takes 40min in bidirectional mode